

EICROC Project: update (March 5th, 2024)

- > Scrutinizing TDC data shifting External Trigger for all 16 channels: didn't have the time to work further on it...
- Working on a *complete* proposal (Step 2 of the French National Agency, 20 pages) to be submitted March 28th to try to obtain a budget to contribute to EICROC2 production + 3 years post-doctoral position at IJCLab.
- **EICROCO** chips
 - Feb. 20th, 2024: **24 EICROCO** ASICs were delivered to BNL in view of hybridation (EICROCO+AC-LGAD)
- **20** 10 pieces Updated EICROCO PCBs (test boards) and Related topics
 - Cabling is being performed at IJCLab: will be finalized tomorrow
 [omitting crossing components to allow for the wire-bonding]
 - 3 PCBs will be sent shortly to IPHC (Strasbourg, France) to wire-bond an EICROCO
 We propose to first test this configuration (board operational)
 - * before wire-bonding EICROCO & AC-LGAD
 - * ordering 10 more PCBs
 - 3 PCBs will be sent shortly to BNL with associated crossing components
 - Some AC-LGAD sensors (from BNL) will be transferred to CERN next week to be given to IJCLab

[2 PCBs are intended to be sent later on to IPHC (Strasbourg, France) to wire-bond an EICROCO + AC-LGAD] (AC-LGAD sensors provided by BNL)

[2 PCBs will wait for hybrids from BNL. They will be sent to IPHC (Strasbourg, France) for wire-bonding]